



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D  <i>* : Required Field</i>

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2012-12-12
<b>Contact Name *</b>	Refer to "Supplier Comment" section	<b>Contact Title</b>	Refer to "Supplier Comment" section
<b>Contact Phone *</b>	Refer to "Supplier Comment" section	<b>Contact Email *</b>	Refer to "Supplier Comment" section
<b>Authorized Representative *</b>	Antonella Lanzafame	<b>Representative Title</b>	AMS/IPD Materials Declaration Champion)
<b>Representative Phone *</b>	Refer to "Supplier Comment" section	<b>Representative Email *</b>	Refer to "Supplier Comment" section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/internet/com/support/online_tech_support.jsp">http://www.st.com/internet/com/support/online_tech_support.jsp</a>		

**Uncertainty Statement**


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Legal Statement			
<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard

**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STPS20200CG-TR	7SD2*ZB1P12K	A	SH1A	2012-12-12
Amount	UoM	Unit type	ST ECOPACK Grade	
1380.00	mg	Each	ECOPACK® 1	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	245	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used c	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SIP	10.20,9.15,4.5	2	gull wing	
Comment				

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	false
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList :REACH-18 June 2012				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	75D2*2B1P12K					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
die (s)	Other inorganic materials	12.402	mg	supplier	die	Silicon (Si)	7440-21-3		11.867	mg	956862	#DIV/0!
die (s)				supplier	metallization	Aluminium (Al)	7429-90-5		0.306	mg	24673	#DIV/0!
die (s)				supplier	metallization	Titanium (Ti)	7440-32-6		0.011	mg	887	#DIV/0!
die (s)				supplier	metallization	Tungsten (W)	7440-33-7		0.018	mg	1451	#DIV/0!
die (s)				supplier	metallization	Nickel (Ni)	7440-02-0		0.013	mg	1048	#DIV/0!
die (s)				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.075	mg	6047	#DIV/0!
die (s)				supplier	back side metallization	Chromium (Cr)	7440-47-3		0.01	mg	806	#DIV/0!
die (s)				supplier	back side metallization	Gold (Au)	7440-57-5		0.025	mg	2016	#DIV/0!
die (s)				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.072	mg	5806	#DIV/0!
die (s)				supplier	back side metallization	Vanadium (V)	7440-62-2		0.005	mg	403	#DIV/0!
Leadframe	Copper & its alloys	792.498	mg	supplier	alloy	Copper (Cu)	7440-50-8		788.668	mg	995167	#DIV/0!
Leadframe				supplier	alloy	Iron (Fe)	7439-89-6		0.363	mg	458	#DIV/0!
Leadframe				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.663	mg	837	#DIV/0!
Leadframe				supplier	metallization	Nickel (Ni)	7440-02-0		2.804	mg	3538	#DIV/0!
Leadframe		0.017	mg	supplier	metallization	Phosphorus (P)	12185-10-3		0.017	mg	1000000	#DIV/0!
Soft solder	Solder	8.671	mg	JIG R	solder	Lead (Pb)	7439-92-1	7a-Lead in high me	8.281	mg	955022	#DIV/0!
Soft solder				supplier	solder	Silver (Ag)	7440-22-4		0.217	mg	25026	#DIV/0!
Soft solder				supplier	solder	Tin (Sn)	7440-31-5		0.173	mg	19952	#DIV/0!
Bonding wire	Other inorganic materials	4.05		supplier	wire	Aluminium (Al)	7429-90-5		4.05	mg	1000000	#DIV/0!
encapsulation	Other Organic Materials	559.873	mg	supplier	mold compound	Silica, vitreous	60676-86-0		447.898	mg	799999	#DIV/0!
encapsulation				supplier	mold compound	Epoxy Cresol Novolak	29690-82-2		39.191	mg	70000	#DIV/0!
encapsulation				supplier	mold compound	Phenol resin	9003-35-4		22.395	mg	40000	#DIV/0!
encapsulation				supplier	mold compound	Biphenyl epoxy resin	85954-11-6		33.592	mg	59999	#DIV/0!
encapsulation				supplier	mold compound	Antimony Trioxide	1309-64-4		6.719	mg	12001	#DIV/0!
encapsulation				JIG I	mold compound	Brominated Epoxy Resin	40039-93-8		8.398	mg	15000	#DIV/0!
encapsulation				supplier	mold compound	Carbon black	1333-86-4		1.68	mg	3001	#DIV/0!
connections coating	Solder	2.489	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		2.489	mg	1000000	#DIV/0!